


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.		CRP/16/9465
1.3 Title of PCI		Moisture Barrier Bag (MBB) for 3-layer and 4-layer Pre plated frame FPN, SOT, SO & TSSOP REELS AND TUBES
1.4 Product Category		FPN, SOT, SO & TSSOP assembled with 3-layer and 4-layer Pre plated frame
1.5 Issue date		2016-05-09

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	SETTLES JEFF
2.1.2 Phone	+44 1628896222
2.1.3 Email	jeff.settles@st.com
2.2 Change responsibility	
2.2.1 Process Owner	Patrick LOW
2.1.2 Corporate Quality Manager	Veronique LIVACHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New Indirect material part number (same supplier or different supplier): Boxes, trays, carriers, back grinding tape, wafer mounting tape, mold tape, ...	ST Shenzhen (China), ST Bouskoura (Morocco), ST Muar (Malaysia), ST Calamba (Philippines) ST Subcontractors (Carsem Semiconductor, Carsem China, UTAC Thai Limited, NFME, AMKOR ATP3, AMKOR APT1)

4. Description of change

	Old	New
4.1 Description	<p>The reels and tubes of the 3-layer and 4-layer Pre plated frame FPN, SOT, SO & TSSOP packages from ST Shenzhen (China), ST Bouskoura (Morocco), ST Muar (Malaysia), ST Calamba (Philippines) and ST Subcontractors (Carsem Semiconductor, Carsem China, UTAC Thai Limited, NFME, AMKOR ATP3, AMKOR APT1) are packed into the inner box without bag.</p> <p>The reels and tubes of the 4-layer Pre plated frame SO8N & TSSOP8 packages from ST Shenzhen (China) of MMS Group are packed into the inner box with shielding bag (refer to PCI CRP/15/9379).</p> <p>The reels of VFQFPN32, UDFPN8, WDFPN8, UDFPN5 packages from ST Calamba (Philippines) & Amkor subcontractor (Philippines) of MMS Group are packed into the inner box with shielding bag (refer to PCI MMS/16/9678).</p>	<p>The reels and tubes of the 3-layer and 4-layer Pre plated frame FPN, SOT, SO & TSSOP packages from ST Shenzhen (China), ST Bouskoura (Morocco), ST Muar (Malaysia), ST Calamba (Philippines) and ST Subcontractors (Carsem Semiconductor, Carsem China, UTAC Thai Limited, NFME, AMKOR ATP3, AMKOR APT1) will be packed with a Moisture Barrier Bag (MBB).</p>
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	- Form: No change - Fit: No change - Function: No change	

5. Reason / motivation for change

5.1 Motivation	This Moisture Barrier Bag will protect the product during exposure to uncontrolled environment before product usage (transportation/storage).
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	-
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7. Timing / schedule	
7.1 Date of qualification results	2016-05-20
7.2 Intended start of delivery	2016-06-03
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation		
8.1 Description		
8.2 Qualification report and qualification results	In progress	Issue Date

9. Attachments (additional documentations)
9465PpPrdtLst.pdf PCI PPF UPPF MBB bags.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	L6384ED	
	L78L05ACD13TR	
	L78L33ABD-TR	
	LD2985BM30R	
	LM239PT	
	LM393ST	
	LMV321LICT	
	M24256-BWDW6TP	
	M24256-BWMN6TP	
	M24256-DFDW6TP	
	M24256-DFMN6TP	
	M24C01-RMN6TP	
	M24C01-WDW6TP	
	M24C02-WMN6TP	
	M24C16-RMC6TG	
	M24LR04E-RDW6T/2	
	M24M01-RMN6TP	
	M24M02-DRMN6TP	
	M41T00SM6F	
	M41T56M6F	
	M41T81M6F	
	M41T81SM6F	
	M74HC4094RM13TR	
	M95010-WMN6TP	
	M95640-WDW6TP	
	ST1S03PUR	
	ST1S06PUR	
	ST1S32PUR	
	ST202CDR	
	ST3232BTR	
	ST3232EBTR	
	STC4054GR	
	STG3157CTR	
	STLM75DS2F	
	STM1001TWX6F	

	STM6717TWWY6F	
	STM706RM6F	
	STM8S003F3P6TR	
	STM8S103F2P6TR	
	STMP2141STR	
	STMP2171STR	
	STTS75DS2F	
	STWD100NYWY3F	
	TL084CPT	
	TL431ACDT	
	TL431AIDT	
	TS4990IQT	
	TS922AIPT	
	TS922IDT	
	TSH22IDT	
	TSV321RILT	
	TSV611ILT	
	TSV622IDT	
	TSV632IDT	
	UC2843BD1013TR	
	L6386ED	
	L78L05ABD13TR	
	LM311DT	
	LM317LD13TR	
	LM358DT	
	LMV321RIYLT	
	M24C02-RMN6TP	
	M24M01-RMN6P	
	M95512-RDW6TP	
	MC33172DT	
	MC34063ECD-TR	
	ST1S10PUR	
	ST1S31PUR	
	ST232BDR	
	ST3232CDR	
	ST485CDR	
	STM6822SWY6F	
	STM6823SWY6F	
	STM809RWX6F	
	TSV994IDT	
	UC2844BD1013TR	

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